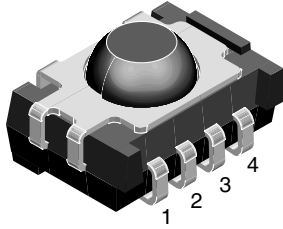


## IR Receiver Module for Light Barrier Systems



16797

### MECHANICAL DATA

#### Pinning:

 1 = GND, 2 = N.C., 3 = OUT, 4 =  $V_S$ 

### FEATURES

- Low supply current
- Photo detector and preamplifier in one package
- Internal filter for 38 kHz IR signals
- Shielding against EMI
- Supply voltage: 2.7 V to 5.5 V
- Visible light is suppressed by IR filter
- Insensitive to supply voltage ripple and noise
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



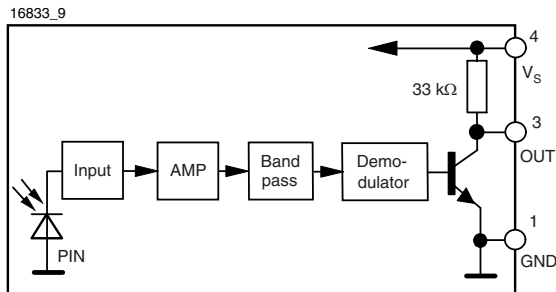
### DESCRIPTION

The TSOP5038 is a compact SMD IR receiver for sensor applications. It has a high gain for IR signals at 38 kHz. The detection level does not change when ambient light or strong IR signals are applied. It can receive continuous 38 kHz signals or 38 kHz bursts.

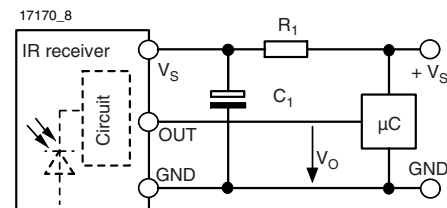
### PARTS TABLE

CARRIER FREQUENCY	SENSOR APPLICATIONS
38 kHz	TSOP5038

### BLOCK DIAGRAM



### APPLICATION CIRCUIT



The external components  $R_1$  and  $C_1$  are optional to improve the robustness against electrical overstress (typical values are  $R_1 = 100 \Omega$ ,  $C_1 = 0.1 \mu\text{F}$ ). The output voltage  $V_O$  should not be pulled down to a level below 1 V by the external circuit. The capacitive load at the output should be less than 2 nF.



ABSOLUTE MAXIMUM RATINGS (1)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage (pin 4)		$V_S$	- 0.3 to + 6.0	V
Supply current (pin 4)		$I_S$	5	mA
Output voltage (pin 3)		$V_O$	- 0.3 to 5.5	V
Voltage at output to supply		$V_S - V_O$	- 0.3 to ( $V_S + 0.3$ )	V
Output current (pin 3)		$I_O$	5	mA
Junction temperature		$T_j$	100	°C
Storage temperature range		$T_{stg}$	- 25 to + 85	°C
Operating temperature range		$T_{amb}$	- 25 to + 85	°C
Power consumption	$T_{amb} \leq 85 \text{ °C}$	$P_{tot}$	10	mW

**Note**

(1) Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability.

ELECTRICAL AND OPTICAL CHARACTERISTICS (1)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply current (pin 4)	$E_v = 0, V_S = 5 \text{ V}$	$I_{SD}$	0.65	0.85	1.05	mA
	$E_v = 40 \text{ klx, sunlight}$	$I_{SH}$		0.95		mA
Supply voltage		$V_S$	2.7		5.5	V
Transmission distance	$E_v = 0$ , test signal see fig. 1, IR diode TSAL6200, $I_F = 400 \text{ mA}$	$d$		30		m
Output voltage low (pin 3)	$I_{OSL} = 0.5 \text{ mA}, E_e = 2 \text{ mW/m}^2$ , test signal see fig. 1	$V_{OSL}$			100	mV
Minimum irradiance	Pulse width tolerance: $t_{pi} - 5/f_0 < t_{po} < t_{pi} + 6/f_0$ , test signal see fig. 1	$E_e \text{ min.}$		0.5	1	$\text{mW/m}^2$
Maximum irradiance	$t_{pi} - 5/f_0 < t_{po} < t_{pi} + 6/f_0$ , test signal see fig. 1	$E_e \text{ max.}$	30			$\text{W/m}^2$
Directivity	Angle of half transmission distance	$\varphi_{1/2}$		$\pm 50$		deg

**Note**

(1)  $T_{amb} = 25 \text{ °C}$ , unless otherwise specified

**TYPICAL CHARACTERISTICS**

$T_{amb} = 25 \text{ °C}$ , unless otherwise specified

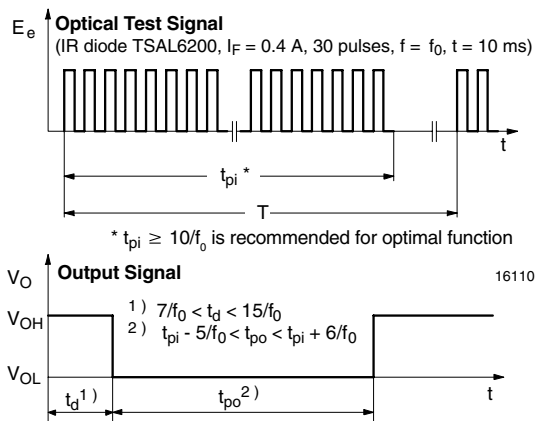


Fig. 1 - Output Active Low

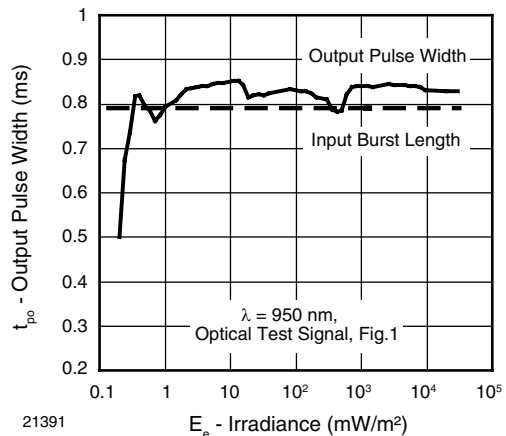


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

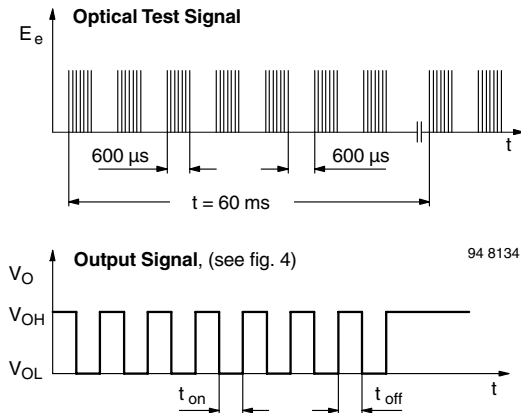


Fig. 3 - Output Function

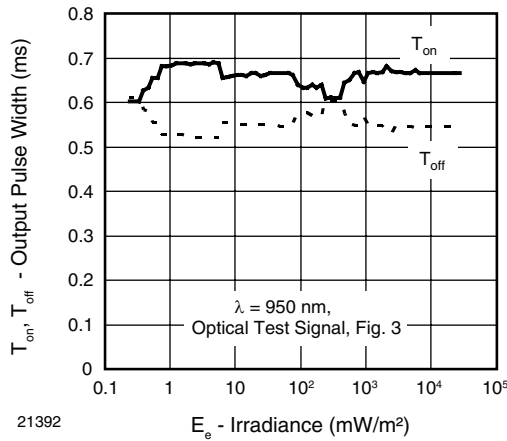


Fig. 4 - Output Pulse Diagram

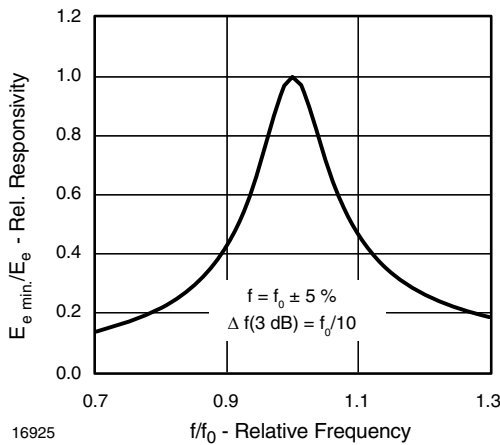


Fig. 5 - Frequency Dependence of Responsivity

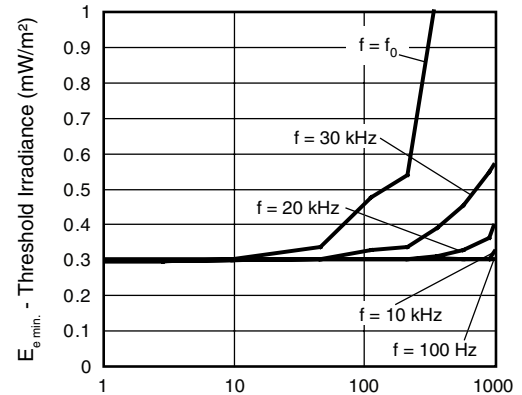


Fig. 6 - Sensitivity vs. Supply Voltage Disturbances

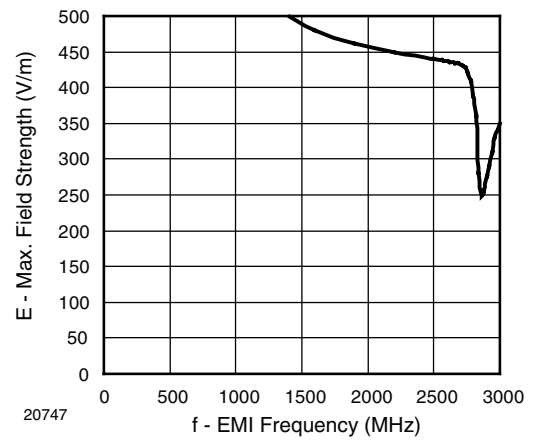


Fig. 7 - Sensitivity vs. Electric Field Disturbances

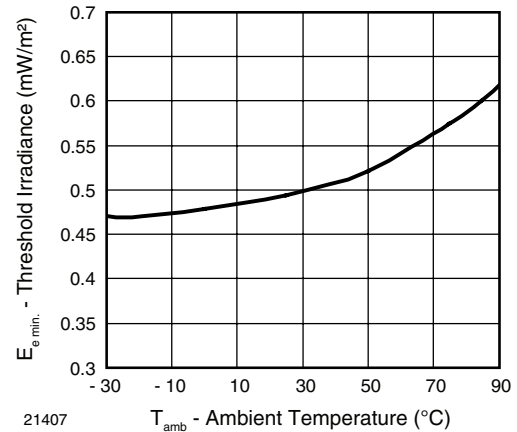


Fig. 8 - Sensitivity vs. Ambient Temperature

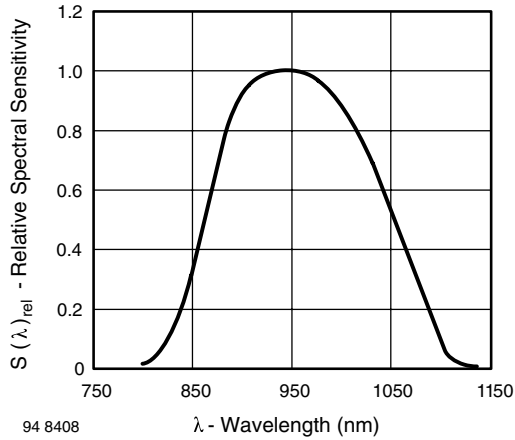


Fig. 9 - Relative Spectral Sensitivity vs. Wavelength

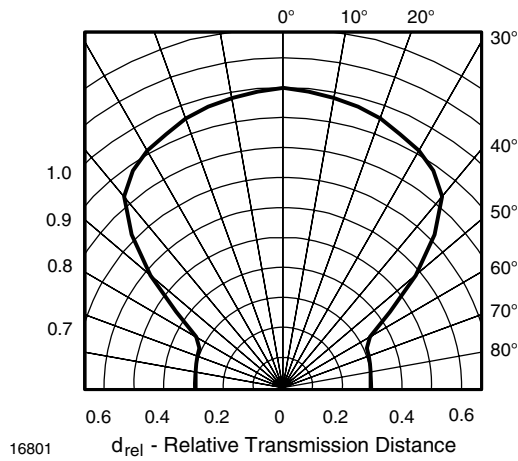


Fig. 10 - Horizontal Directivity

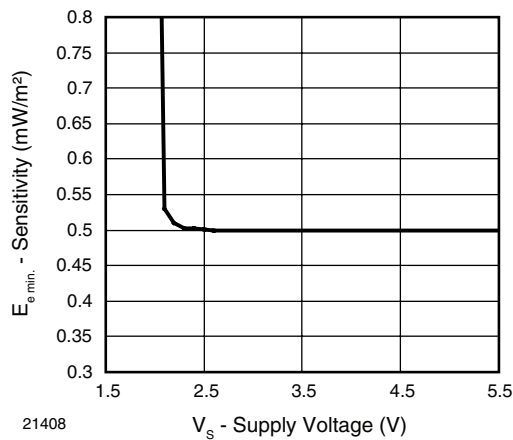
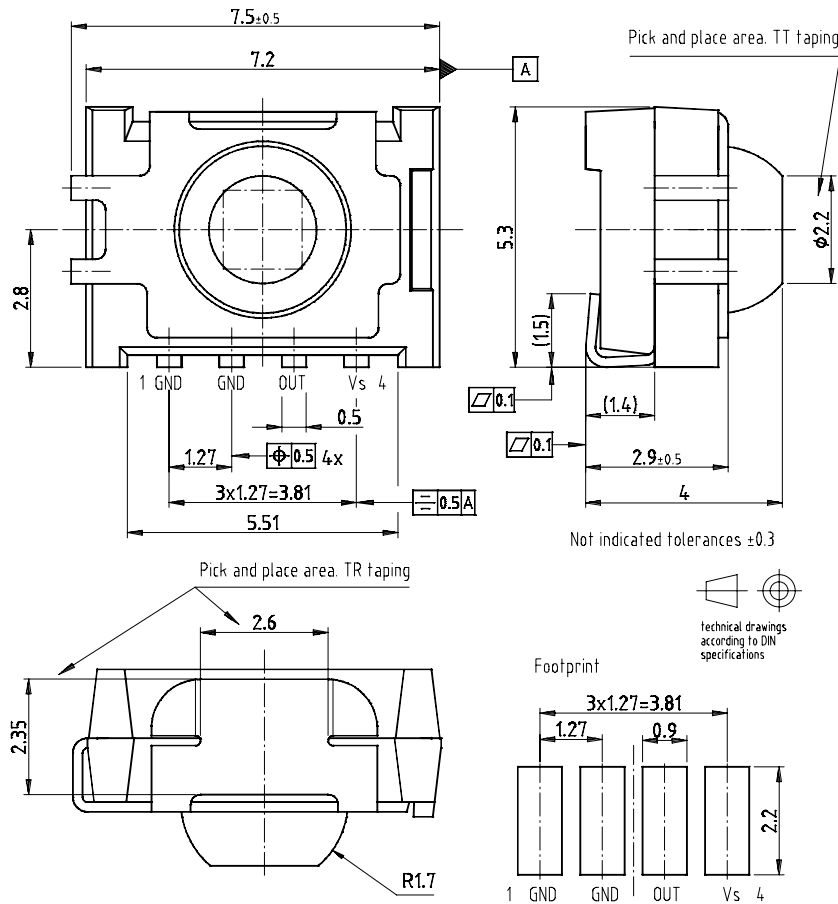


Fig. 11 - Sensitivity vs. Supply Voltage

**PACKAGE DIMENSIONS** in millimeters


Drawing-No.: 6.544-534.101-4  
Issue: 5; 28.10.02

16776

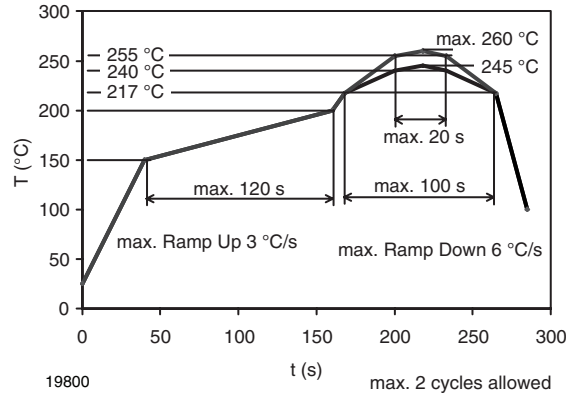
**ASSEMBLY INSTRUCTIONS**
**Reflow Soldering**

- Reflow soldering must be done within 72 h while stored under a max. temperature of  $30^\circ\text{C}$ , 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below  $260^\circ\text{C}$ . The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

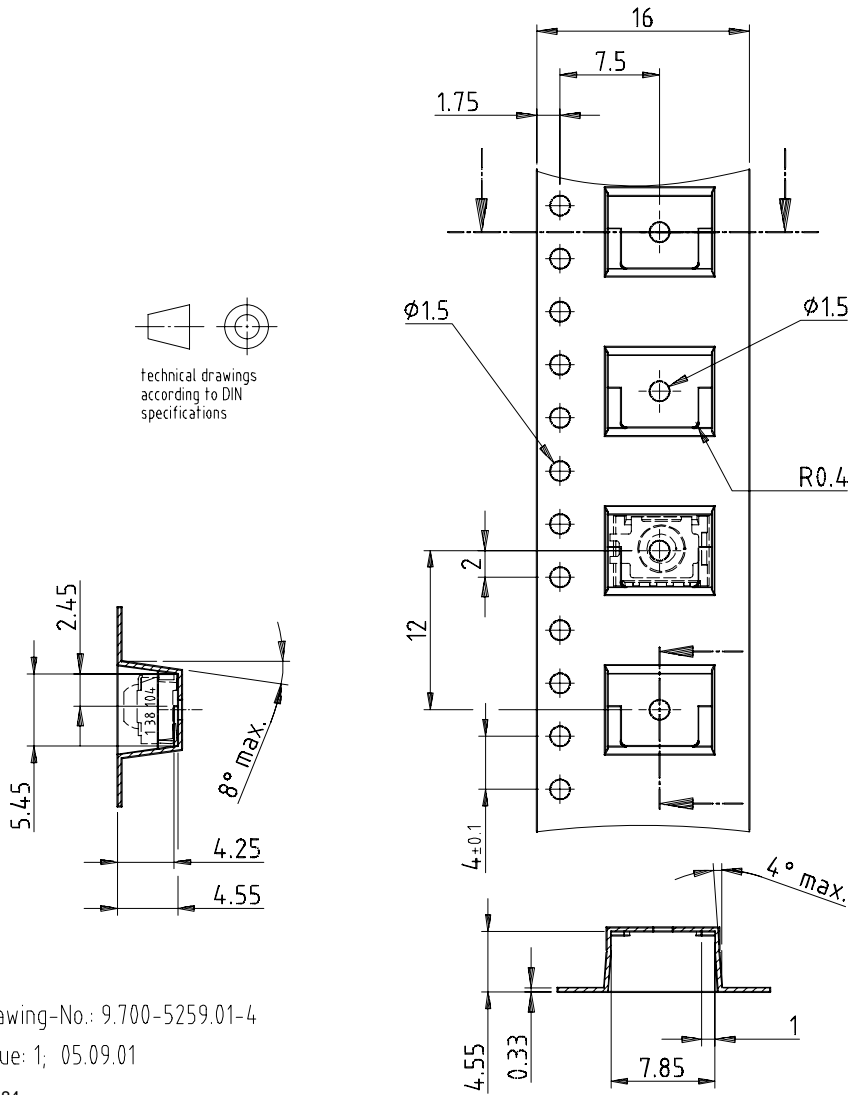
**Manual Soldering**

- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below  $300^\circ\text{C}$
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off

**VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE**

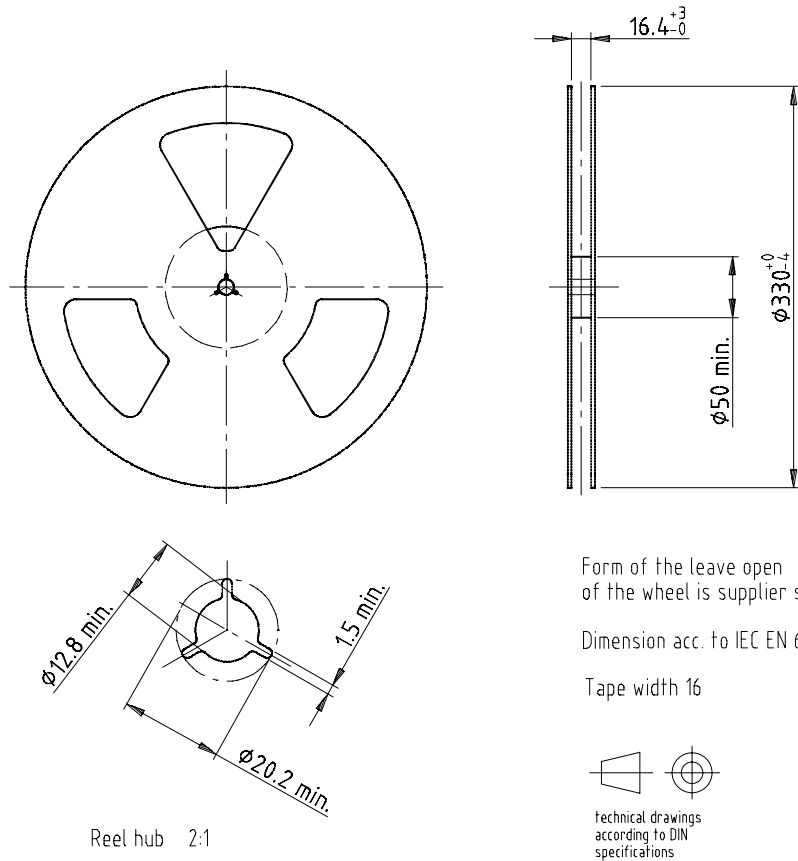


**TAPING VERSION TSOP..TT Dimensions in millimeters**





**REEL DIMENSIONS** in millimeters



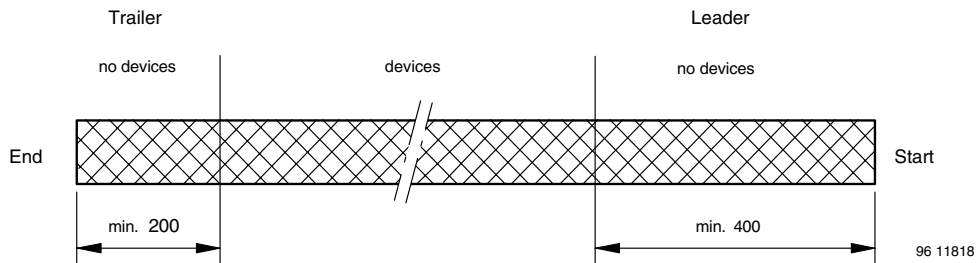
Drawing refers to following types: Reel for blister carrier tape Version B

Drawing-No.: 9.800-5052.V2-4

Issue: 1; 07.05.02

16734

**LEADER AND TRAILER** Dimensions in millimeters



**COVER TAPE PEEL STRENGTH**

According to DIN EN 60286-3

0.1 to 1.3 N

300 ± 10 mm/min.

165° to 180° peel angle

**LABEL**

**Standard bar code labels for finished goods**

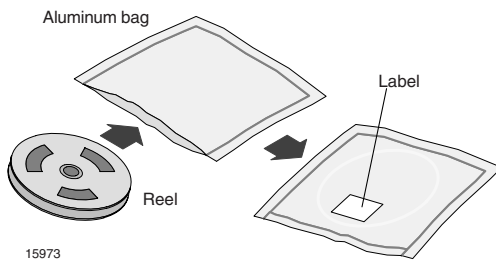
The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.



<b>VISHAY SEMICONDUCTOR GMBH STANDARD BAR CODE PRODUCT LABEL (Finished Goods)</b>		
<b>PLAIN WRITTING</b>	<b>ABBREVIATION</b>	<b>LENGTH</b>
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
<b>LONG BAR CODE TOP</b>	<b>TYPE</b>	<b>LENGTH</b>
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
<b>SHORT BAR CODE BOTTOM</b>	<b>TYPE</b>	<b>LENGTH</b>
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

### DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



### FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

### RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

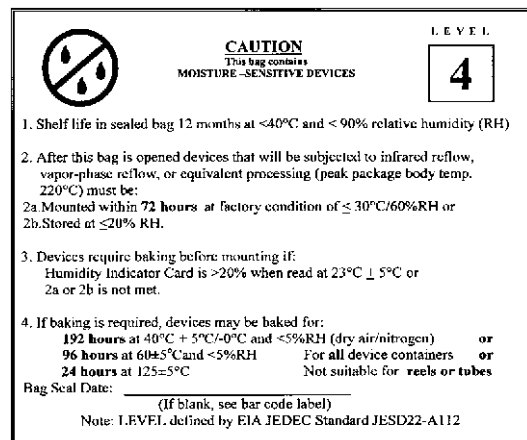
After more than 72 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C/ - 0 °C and < 5 % RH (dry air/nitrogen) or

96 h at 60 °C + 5 °C and < 5 % RH for all device containers or 24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC standard JESD22-A112 level 4 label is included on all dry bags.



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Example of JESD22-A112 level 4 label



## ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electro-static sensitive devices warning labels are on the packaging.

## VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.



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**OZONE DEPLETING SUBSTANCES POLICY STATEMENT**

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design  
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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